AMENDMENTS TO THE SPECIFICATION

Please replace the paragraph beginning at page 3, line 24, with the following rewritten paragraph.

--Due to this difference in construction, in the former case, as shown in Fig. 1A, light impinging from the back surface 31 side is blocked by the package 32, whereas, in the latter case, as shown in Fig. 1B, light directly impinges upon the back surface 31 of the imaging element 30. In this situation, the silicon substrate (silicon wafer or the like) often used as the base substrate of the imaging element 30 transmits a light having an optically large wavelength (large wavelength band from the infrared range ~~o~~ of the visible light range). Thus, in the latter case, not only the incident light from the light receiving portion side (front surface side) of the imaging element 30 but also light impinging from the element back surface 31 is transmitted through the interior of the element, and this transmitted light reaches the light receiving portion and is detected, whereby the generation of a ghost image is caused.--

Please replace the paragraph beginning at page 11, line 15, with the following rewritten paragraph.

--The optical filter 20 serves as a so-called infrared cutting filter to cut off the infrared portion, for example, of the incident light impinging through the diaphragm 19A. This optical filter 20 is fixed to a position near the forward end of ~~he~~ the lens barrel 19 in close vicinity of the diaphragm portion 19A. The lens 21 serves to effect image formation at the light receiving portion 15 of the imaging element 11 from the light impinging through the diaphragm portion 19A and the optical filter 20. This lens 21 is mounted to the interior of the lens barrel 19 together with the optical filter 20 with positioning being effected using the diaphragm portion 19A as a reference.--